

AMENDMENTS TO THE CLAIMS

Cancel claims 2-5 and 33-35 without prejudice

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-5. (canceled)

6. (currently amended) ~~The apparatus of claim 2,~~

An apparatus comprising:

a substrate;

a pair of signal traces formed directly on the substrate and spaced from each other;

a filler material directly on the substrate and between the signal traces, the filler material having a dielectric constant that is higher than a dielectric constant of a material of which the substrate is formed; and

a solder mask layer directly on the signal traces and directly on the filler material, the dielectric constant of the filler material being higher than a dielectric constant of the solder mask layer;

wherein the filler material has a height that is substantially equal to a height of the signal traces.

7. (currently amended) The apparatus of claim 2 6, wherein the filler material has a dielectric constant in excess of 4.

8-28 (canceled)

29. (currently amended) The apparatus of claim 2 6, wherein the filler material includes polyvinylidene difluoride.

30. (currently amended) The apparatus of claim 2 6, further comprising:
a metal ground plane on an opposite side of the substrate from the signal traces.

31. (currently amended) An apparatus comprising:

a substrate;

a pair of signal traces formed on the substrate and spaced from each other;

a filler material on the substrate and between the signal traces, the filler material having a dielectric constant that is higher than a dielectric constant of a material of which the substrate is formed; and

a metal ground plane on an opposite side of the substrate from the signal traces;

wherein the filler material has a height that is substantially equal to a height of the signal traces.

32. (previously presented) The apparatus of claim 31, wherein:

the signal traces are formed directly on the substrate;

the filler material is directly in contact with the substrate; and

the ground plane is directly in contact with the substrate.

33-35. (canceled)

36. (new) The apparatus of claim 6, wherein the substrate includes a resin in which fibers are embedded, the dielectric constant of the filler material being higher than a dielectric constant of the resin.

37. (new) The apparatus of claim 6, wherein the signal traces are formed of copper.

38. (new) The apparatus of claim 6, wherein the filler material substantially fills a space between the signal traces.